

Dynamic Life demands versatile Test Technology

Salland Test Technology Symposium 2019

SEPT. 26 - SEPT. 27

Welcome!

2nd Test Technology Symposium

A warm welcome to our guests!

TERADYNE

nexperia

Abrel Products
advanced burn-in and reliability

ADVANTEST



EDA Industries

boschman
advanced packaging technology

amun

dizain-sync

ICSense
THE IC DESIGN COMPANY

Adesto

EquipIC supply chain*

ELEVATE
SEMICONDUCTOR

Chroma

bruco
INTEGRATED CIRCUITS

BITS&CHIPS

MASER
ENGINEERING

NATIONAL INSTRUMENTS

NEWAYS

EnSilica

yieldHUB

PTSL

elmos

GRAPHCORE

Panasonic INDUSTRY

UNIVERSITY OF TWENTE.

BCSEMI NL
MINDCET.
Custom Integrated Power Management Solutions

TEV
testevolution.com

Cohu

TU/e EINDHOVEN UNIVERSITY OF TECHNOLOGY

phix PHOTONICS ASSEMBLY

imec

Reid Ashman

C.C.P.

AXIGN

ficonTEC
photonics assembly & testing

Lime microsystems

rood

eazy works

oost.nl

Salland Engineering at a glance



Test Application Solutions

- *Fast & Qualified new product introduction*



ATE Instrument Solutions

- *Industrializing your Test Solutions*



Supply Chain & Test Services

- *Delivering qualified Parts, Products & ATE Solutions*



Supply Chain & Test Services

Delivering qualified Parts, Products & ATE Solutions



Supply Chain & Production Test Services

Quick, Reliable & Independent Production Test including Test Engineering

ATE equipment

Teradyne UltraFLEX 24-slot

- ▶ RF UltraWAVE24

Teradyne UltraFLEX 12-slot

Teradyne FLEX-RF & μ FLEX

Teradyne J750

- ▶ 1024 channel head

Exploring other platforms

Handling equipment

Wafer Probers (room to 150C)

- ▶ TEL P-12XLm for 6, 8 & 12" wafers with hot chuck
- ▶ TSK-UF200 for 6" and 8" wafers

Device Handlers (-60 to 150C)

- ▶ Exatron 903 Engineering handler, 3-temp.
- ▶ ESMO Talos Engineering handler, 3-temp.
- ▶ Chroma 3160C Production handler 3-temp.

Thermonics T-2500E

Services

Sample to mid volume testing

Final test and Wafer test

- ▶ 6, 8 and 12"

Characterization

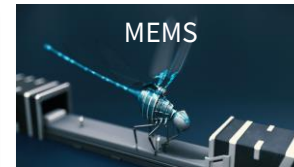
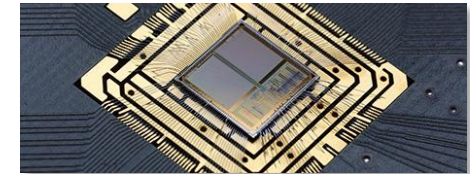
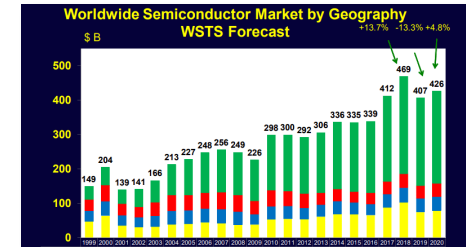
Quality & Reliability analysis



Today's Challenges

Many trends that push up development costs of ATE



- Semi market is growing but with 'ripples'
- Chip complexity increases
- ATE market is 'Stabilizing'
- Shorter life times
- New markets coming up
 - ▶ Specifications not well defined yet



Test Solution Development costs go up → STTC idea born!

Intro/update to STTC

To boost your development by new Test Technology

- Last year we opened Salland Test Technology Center to “*Bridge to the future*”
 - ▶ Acquisition of  **APPLICOS** a SALLAND Engineering Company to add 25+ years of Analog & PXI experience
- Development of “fundamental test technology”
 - ▶ Including creation of IP-blocks ready to be used in products 
 - ▶ POC of complete test channels
- Exploring new test methods & technology to provide you
 - ▶ Faster Time-to-Market, Less risk and Lower costs to develop your products
 - ▶ *As we did over the last 27 years but at higher speed*
- Test industrializing and offering custom(er) solutions

Key is: Partnerships and collaboration

Close cooperation with MASER Engineering

Combined experience in Test, Qualification and FA Engineering → in the past, present & future



SALLAND Engineering

- ▶ Test program & hardware development
- ▶ Electrical test of Qualification & RMA devices
- ▶ Broad range of testers available and accessible (including probers and handlers)

MASER Engineering

- ▶ Qualification, FA and RMA handling
- ▶ Full range of qualification equipment
- ▶ State of the art Physical Analysis lab for FA and RMA handling

- Seamless logistic flow between Salland and MASER, both located in the Netherlands (< 80km).
- Large customer base of IC development companies in OEM, IDM, Fabless, Design houses
- Know-how of qualification (Automotive (AEC-Q100) Industrial/Consumer (JEDEC))
- Both work independently with other test-houses and qualification labs

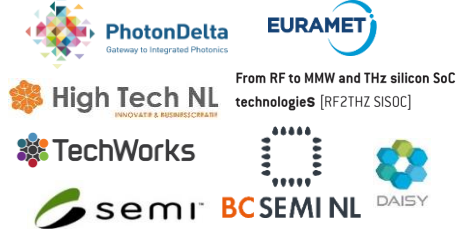
Today: our role in the Test Technology Eco system...

Close cooperation with end customers and partners to deliver solutions that work

Technical Universities



Consortia/Tech programs



Manufacturing Partners

Technology Partners

ATE & PXI Manufacturers



IDM, Fables, Subcons



...makes us Partner of industry market leaders



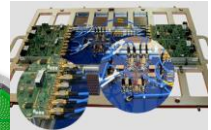
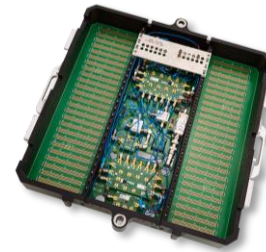
STTC projects

Building future-proof Test IP & Tooling to deliver **enabling Technology**

Salland Innovative milestones

Test Innovation over the last 25 years

- 1999: (First) protocol aware
- 2000: First Bluetooth production program
- 2003: 24 → 256 DC channels for uC/CC
- 2004: 30 → 192 DC channels for Cellphone Power management
- 2007: 16 → 72 VI channels for Tablets
- 2013: 32Gbps SerDes on Catalyst/93k
- 2015: RF-modules to deliver 30GHz on Flex to Radar- Array
- Applicos: OEM MEMS test instrument



New and ongoing developments

Tooling and Test Technology that cover the real needs

- DPLUS – Tool for quick and advanced Data Analysis
- DPIN – High Density, low-cost Pin channel up to 500MHz
- LOW-CAPA – MEMS Testing without physical stimulus
 - ▶ Extreme low current & capacitance test circuitry
- SerDes – Test modules up to 100+Gb (PAM4/x)
 - ▶ Including ATE-drivers, integration and application support
- Photonics – Exploring Test technologies together with our partners
- High Density DPS IP based on ElevATE component

DPLUS: Tool for quick and advanced Data Analysis

Easy to find “the needle in the haystack”

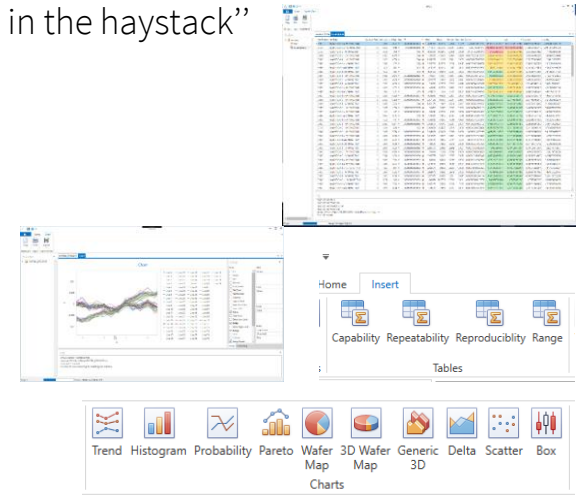
Tool for both Application and Instrument Engineering

- ▶ Quick analysis of large amounts of data
- ▶ Easy site/channel correlation & investigation → find the “needle in the haystack”

Made by the inventors & creators of SEDANA

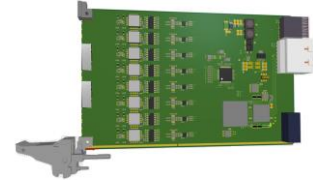


Not for plant optimization
or process control



LOW-CAPA: Extreme Low Capacitance measurement IP

Addressing the MEMS, Sensor & IoT Market



Challenge: Test MEMS without physical stimulus

- ▶ Small capacitance and current
- ▶ Correlation between physical and electrical stimulus

Our approach

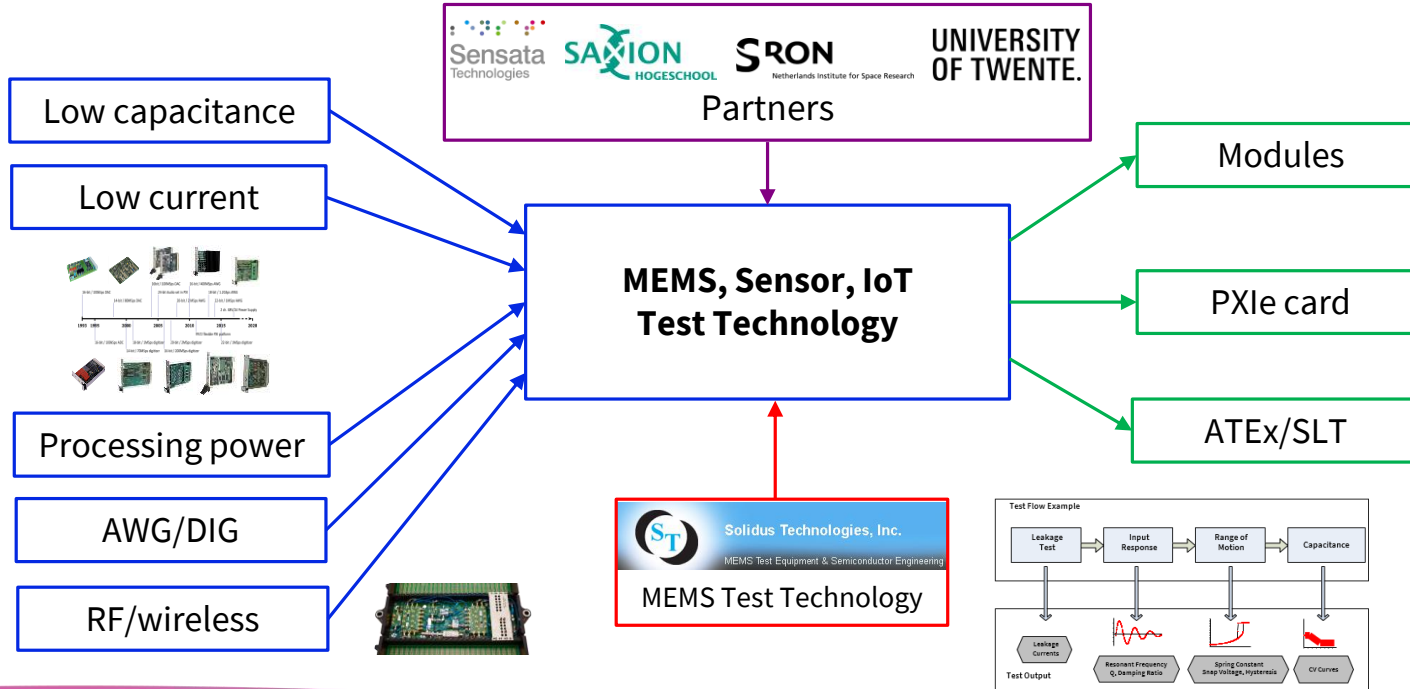
- ▶ Low capacitance and current IP
- ▶ Working with several stakeholders to prove PoC

Made our own MEMS device

Instrument Target specification	
Capacitance Range	±5pF (0fF to 5000 fF diff.)
Settling time	3ms
Accuracy	~4fF
Resolution	18 bit (≈ 40 aF)
Carrier Frequency	30kHz to 2MHz
Carrier Waveform	Square
Carrier Amplitude	0.5V, 1V, 1.5V, 2V (rms)
Noise	±4fF
V DC Bias	±15V
No. of DC Bias Ch.	8
Number of Meas. Ch.	8
Phase Angle Meas.*	Not Supported
Max. cable length	1.0m

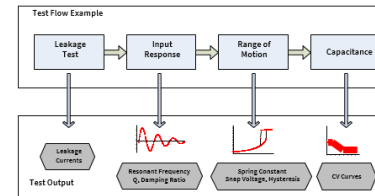
Salland will combine IP to offer new solutions

Most of the IP is already developed or is ongoing and needs to be combined



Target markets

- ▶ MEMS
- ▶ IoT
- ▶ Sensors



DPIN - Challenges in IO channel development

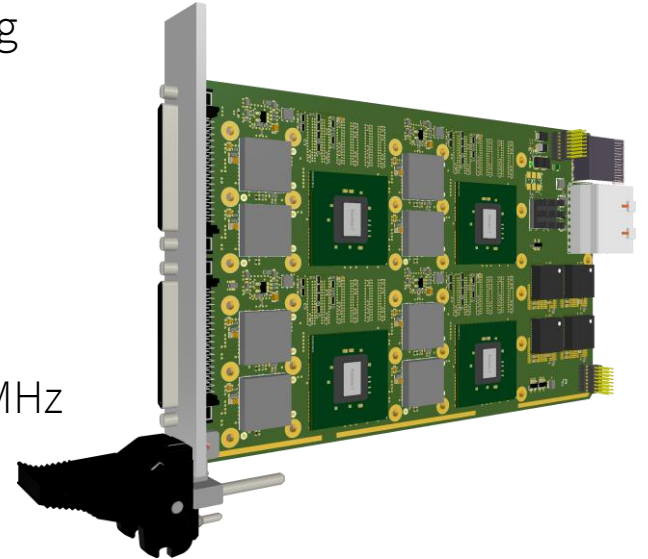
Development of high density & low cost IO - IP

Challenge: Get as many IO channels on a card as possible

- ▶ Space, Power, Cooling, Connections/interfacing

Our approach

- ▶ Evaluation kits
- ▶ POC 8 channels
 - FPGA based timing generator
- ▶ Test vehicle: PXI card format with 64ch @200+MHz



Photonics – New test technology

Challenge: Test optical-electrical components at standard Semi supply chain

- ▶ High speed IO sources
- ▶ Light sources
- ▶ Signal delivery

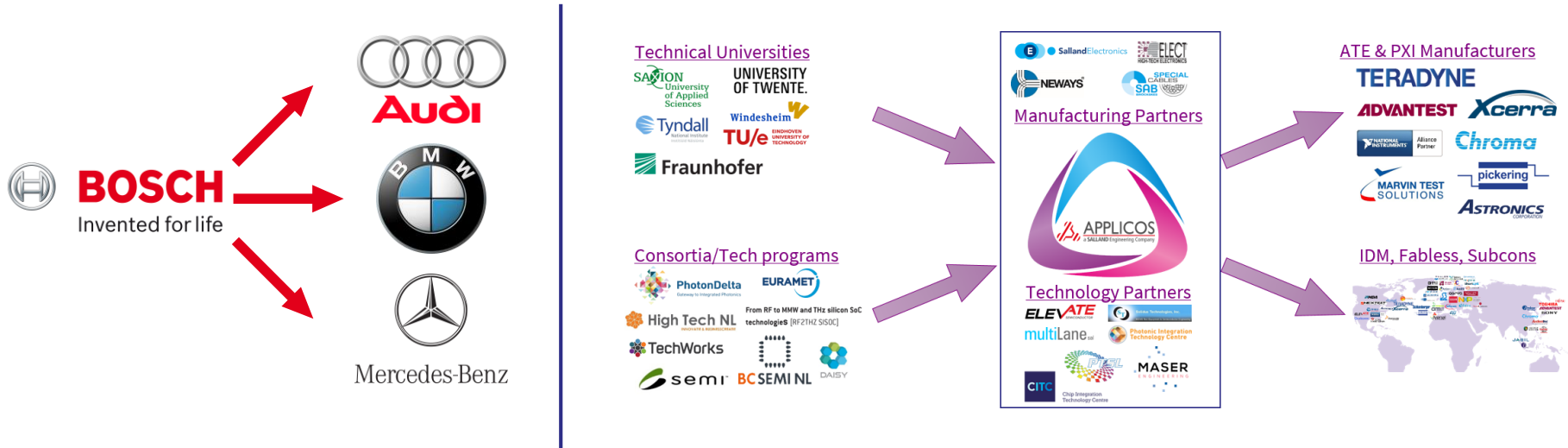
Our approach

- ▶ How to deploy existing technology to deliver a complete solution
- ▶ RAAK: how to interface
- ▶ PITC: data management and deliver test solution

We participate in



STTC ambitions – What BOSCH does for automotive...



Thank you!

